

**Please add the following new claims:**

*Sub-B*  
11. (New) A method according to claim 2, wherein said alternately arranging comprises alternately arranging said two substrates at a pitch which is at least 6 times the thickness of each of the substrates.

12. (New) A method according to claim 11, wherein said alternately arranging comprises alternately arranging said two substrates at a pitch which is at most 100 times the thickness of each of the substrates.

*A 2*  
13. (New) A method according to claim 2, wherein said alternately arranging comprises alternately arranging said two substrates at a pitch which is at least 8 times the thickness of each of the substrates.

14. (New) A method according to claim 13, wherein said alternately arranging comprises alternately arranging said two substrates at a pitch which is at most 30 times the thickness of each of the substrates.

15. (New) A method according to claim 2, wherein said cooling comprises intermittently feeding said two substrates by said feed mechanism at an interval ranging from 1 second to 60 seconds.

16. (New) A method according to claim 2, wherein said cooling comprises cooling each of said substrates for a period of time which is at least 3 minutes.

17. (New) A method according to claim 2, wherein said alternately arranging is performed after a temperature of said substrates is at most 115°C.